

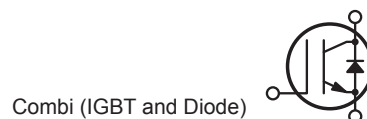
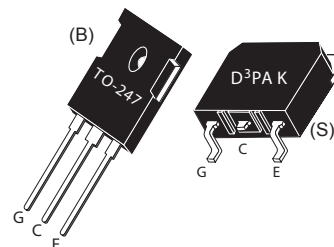


THE DATASHEET OF APT15GT120BRDQ1G

Thunderbolt IGBT®

The Thunderbolt IGBT® is a new generation of high voltage power IGBTs. Using Non-Punch Through Technology, the Thunderbolt IGBT® offers superior ruggedness and ultrafast switching speed.

- Low Forward Voltage Drop
- Low Tail Current
- RBSOA and SCSOA Rated
- High Freq. Switching to 50KHz
- Ultra Low Leakage Current



Combi (IGBT and Diode)

MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT15GT120B_SRDQ1(G)	UNIT
V_{CES}	Collector-Emitter Voltage	1200	Volts
V_{GE}	Gate-Emitter Voltage	± 30	
I_{C1}	Continuous Collector Current @ $T_C = 25^\circ\text{C}$	36	Amps
I_{C2}	Continuous Collector Current @ $T_C = 110^\circ\text{C}$	18	
I_{CM}	Pulsed Collector Current ^① @ $T_C = 150^\circ\text{C}$	45	
SSOA	Switching Safe Operating Area @ $T_J = 150^\circ\text{C}$	45A @ 960V	
P_D	Total Power Dissipation	250	Watts
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_L	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage ($V_{GE} = 0V, I_C = 1mA$)	1200			Volts
$V_{GE(TH)}$	Gate Threshold Voltage ($V_{CE} = V_{GE}, I_C = 0.6mA, T_J = 25^\circ\text{C}$)	4.5	5.5	6.5	
$V_{CE(ON)}$	Collector-Emitter On Voltage ($V_{GE} = 15V, I_C = 15A, T_J = 25^\circ\text{C}$)	2.5	3.0	3.6	
	Collector-Emitter On Voltage ($V_{GE} = 15V, I_C = 15A, T_J = 125^\circ\text{C}$)		3.8		
I_{CES}	Collector Cut-off Current ($V_{CE} = 1200V, V_{GE} = 0V, T_J = 25^\circ\text{C}$) ^②			200	μA
	Collector Cut-off Current ($V_{CE} = 1200V, V_{GE} = 0V, T_J = 125^\circ\text{C}$) ^②			TBD	
I_{GES}	Gate-Emitter Leakage Current ($V_{GE} = \pm 20V$)			480	nA



CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

APT15GT120B_SRDQ1(G)

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{ies}	Input Capacitance	Capacitance $V_{GE} = 0V, V_{CE} = 25V$ $f = 1 \text{ MHz}$		1250		pF
C_{oes}	Output Capacitance			100		
C_{res}	Reverse Transfer Capacitance			65		
V_{GEP}	Gate-to-Emitter Plateau Voltage	Gate Charge $V_{GE} = 15V$ $V_{CE} = 600V$ $I_C = 15A$		10		V
Q_g	Total Gate Charge ^③			105		nC
Q_{ge}	Gate-Emitter Charge			10		
Q_{gc}	Gate-Collector ("Miller") Charge			60		
SSOA	Switching Safe Operating Area	$T_J = 150^\circ C, R_G = 5\Omega, V_{GE} = 15V, L = 100\mu H, V_{CE} = 960V$	45			A
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) $V_{CC} = 800V$ $V_{GE} = 15V$ $I_C = 15A$ $R_G = 5\Omega$ $T_J = +25^\circ C$		10		ns
t_r	Current Rise Time			11		
$t_{d(off)}$	Turn-off Delay Time			85		
t_f	Current Fall Time			35		
E_{on1}	Turn-on Switching Energy ^④			585		μJ
E_{on2}	Turn-on Switching Energy (Diode) ^⑤			800		
E_{off}	Turn-off Switching Energy ^⑥			260		
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{CC} = 800V$ $V_{GE} = 15V$ $I_C = 15A$ $R_G = 5\Omega$ $T_J = +125^\circ C$		10		ns
t_r	Current Rise Time			11		
$t_{d(off)}$	Turn-off Delay Time			95		
t_f	Current Fall Time			42		
E_{on1}	Turn-on Switching Energy ^④			590		μJ
E_{on2}	Turn-on Switching Energy (Diode) ^⑤			1440		
E_{off}	Turn-off Switching Energy ^⑥			340		

THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case (IGBT)			.50	°C/W
$R_{\theta JC}$	Junction to Case (DIODE)			1.18	
W_T	Package Weight		5.9		gm

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② For Combi devices, I_{ces} includes both IGBT and FRED leakages

③ See MIL-STD-750 Method 3471.

④ E_{on1} is the clamped inductive turn-on energy of the IGBT only, without the effect of a commutating diode reverse recovery current adding to the IGBT turn-on loss. Tested in inductive switching test circuit shown in figure 21, but with a Silicon Carbide diode.

⑤ E_{on2} is the clamped inductive turn-on energy that includes a commutating diode reverse recovery current in the IGBT turn-on switching loss. (See Figures 21, 22.)

⑥ E_{off} is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1. (See Figures 21, 23.)

Microsemi Reserves the right to change, without notice, the specifications and information contained herein.

TYPICAL PERFORMANCE CURVES

APT15GT120B_SRDQ1(G)

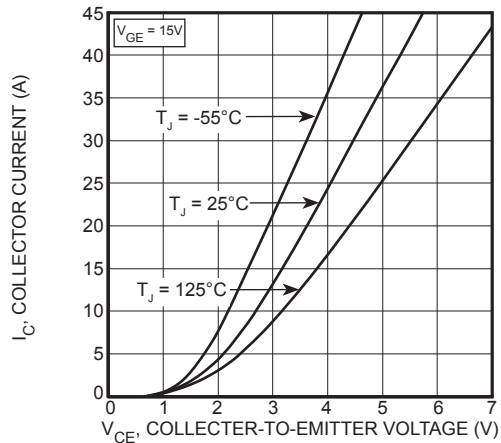


FIGURE 1, Output Characteristics($T_J = 25^{\circ}\text{C}$)

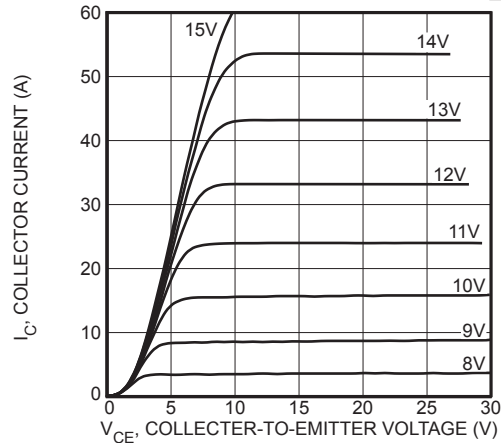


FIGURE 2, Output Characteristics ($T_J = 125^{\circ}\text{C}$)

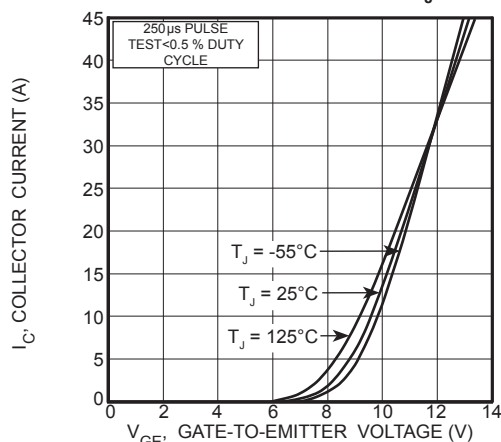


FIGURE 3, Transfer Characteristics

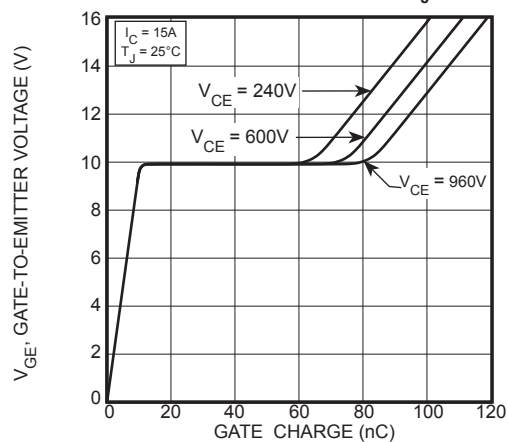


FIGURE 4, Gate Charge

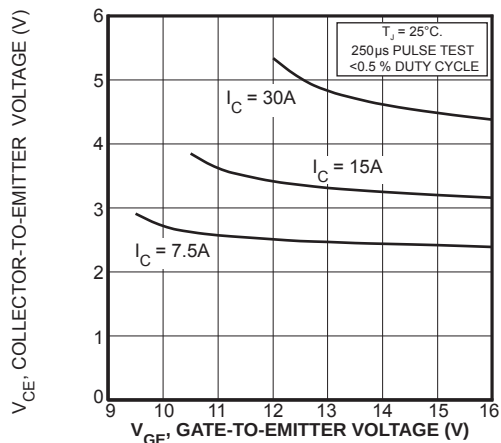


FIGURE 5, On State Voltage vs Gate-to-Emitter Voltage

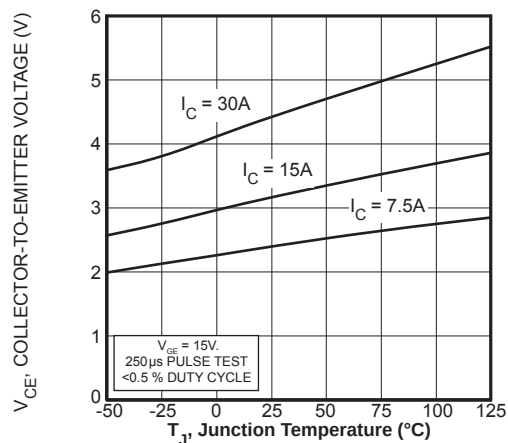


FIGURE 6, On State Voltage vs Junction Temperature

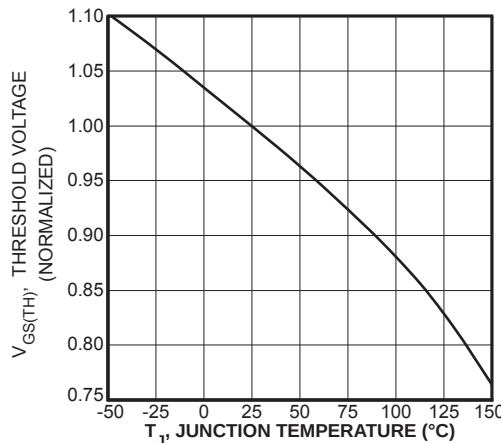


FIGURE 7, Threshold Voltage vs. Junction Temperature

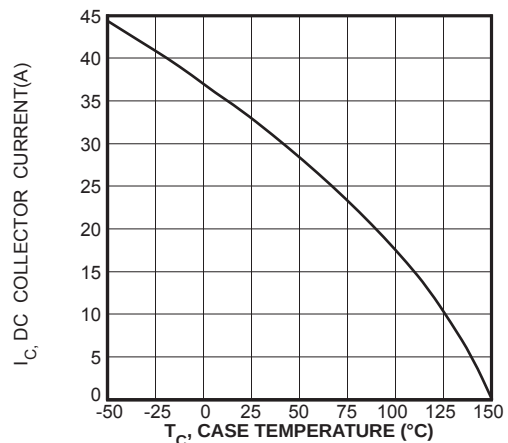


FIGURE 8, DC Collector Current vs Case Temperature

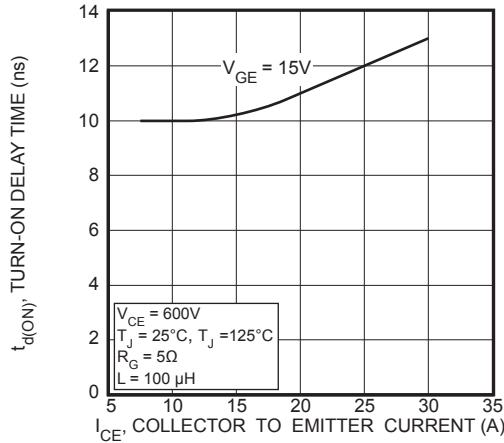


FIGURE 9, Turn-On Delay Time vs Collector Current

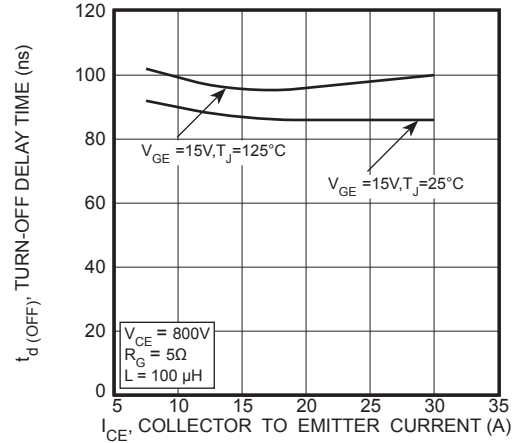


FIGURE 10, Turn-Off Delay Time vs Collector Current

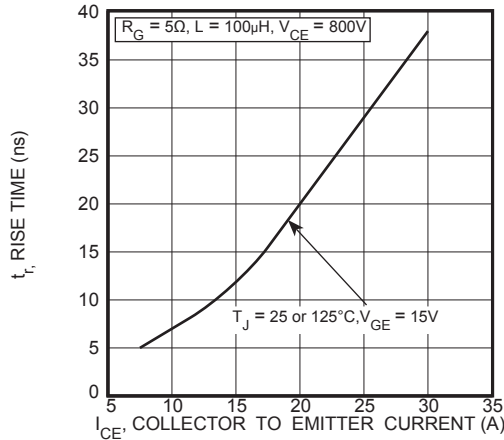


FIGURE 11, Current Rise Time vs Collector Current

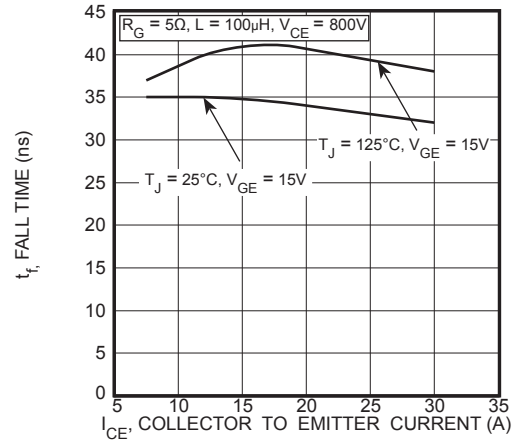


FIGURE 12, Current Fall Time vs Collector Current

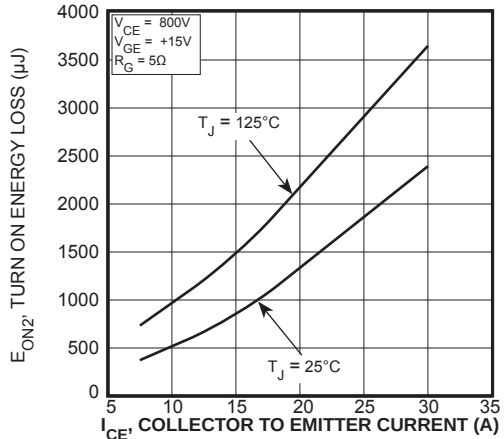


FIGURE 13, Turn-On Energy Loss vs Collector Current

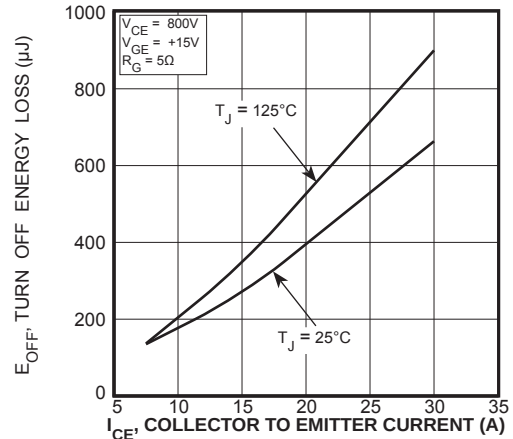


FIGURE 14, Turn Off Energy Loss vs Collector Current

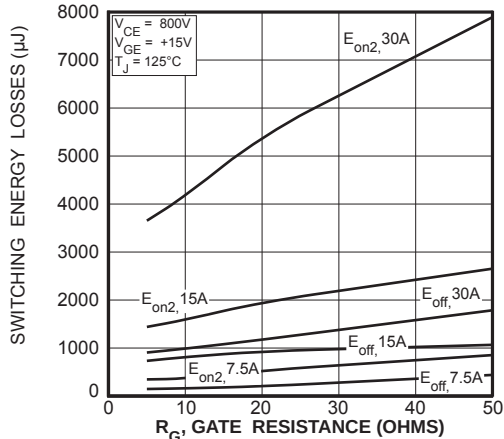


FIGURE 15, Switching Energy Losses vs. Gate Resistance

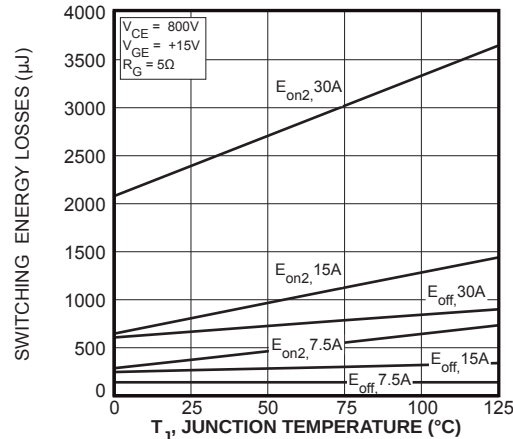


FIGURE 16, Switching Energy Losses vs Junction Temperature

TYPICAL PERFORMANCE CURVES

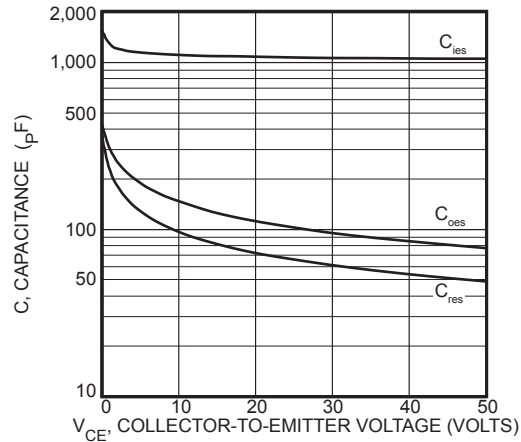


Figure 17, Capacitance vs Collector-To-Emitter Voltage

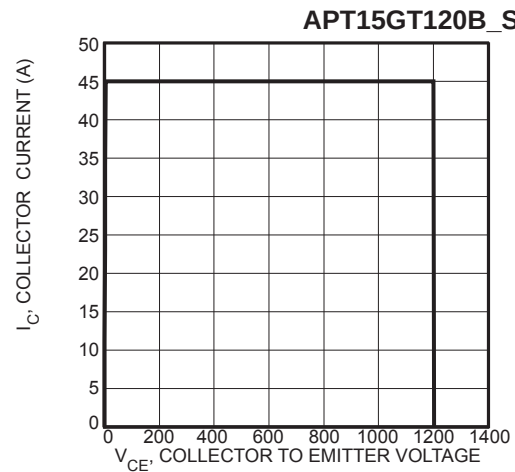


Figure 18, Minimum Switching Safe Operating Area

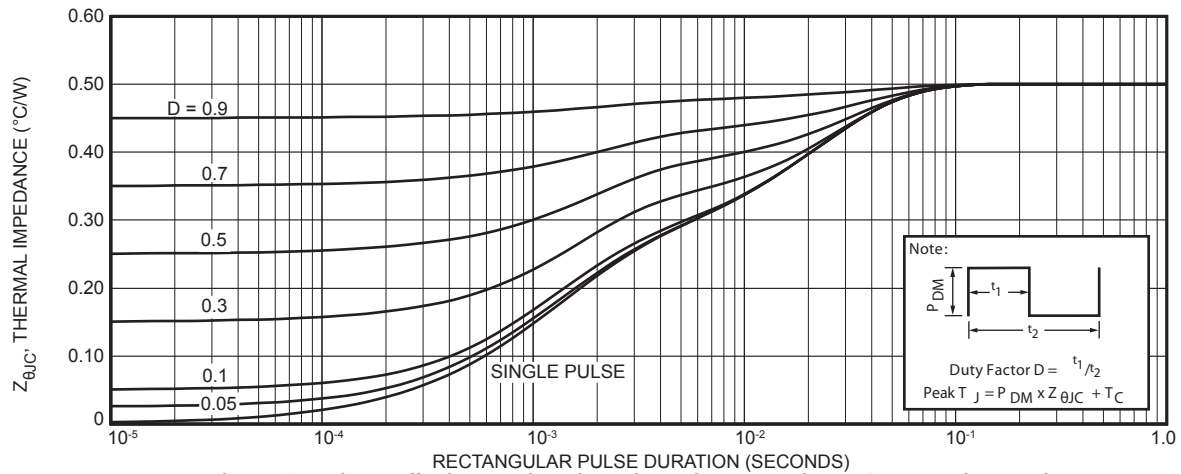


Figure 19, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

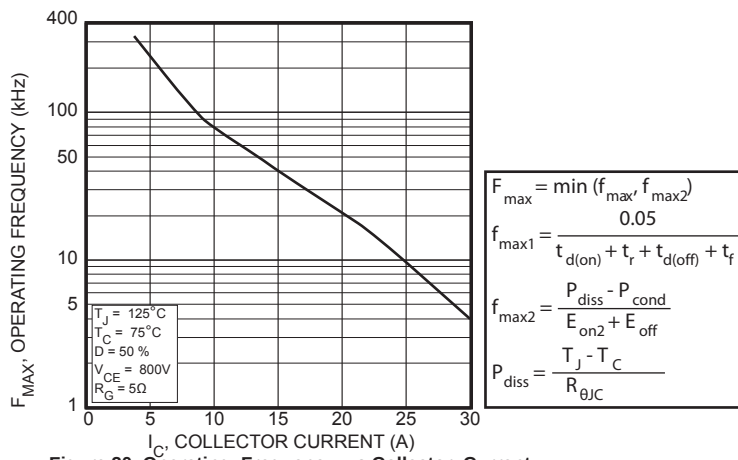


Figure 20, Operating Frequency vs Collector Current

$$F_{max} = \min(f_{max1}, f_{max2})$$

$$f_{max1} = \frac{0.05}{t_{d(on)} + t_r + t_{d(off)} + t_f}$$

$$f_{max2} = \frac{P_{diss} - P_{cond}}{E_{on2} + E_{off}}$$

$$P_{diss} = \frac{T_J - T_C}{R_{\theta JC}}$$

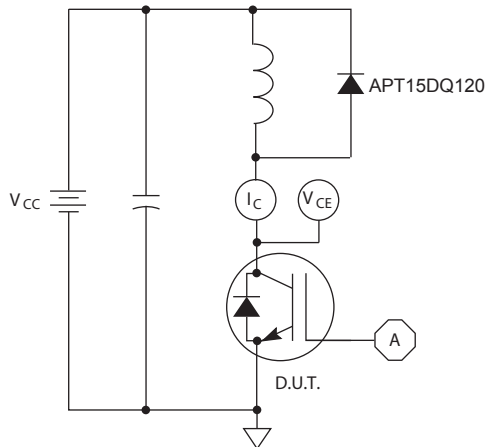


Figure 21, Inductive Switching Test Circuit

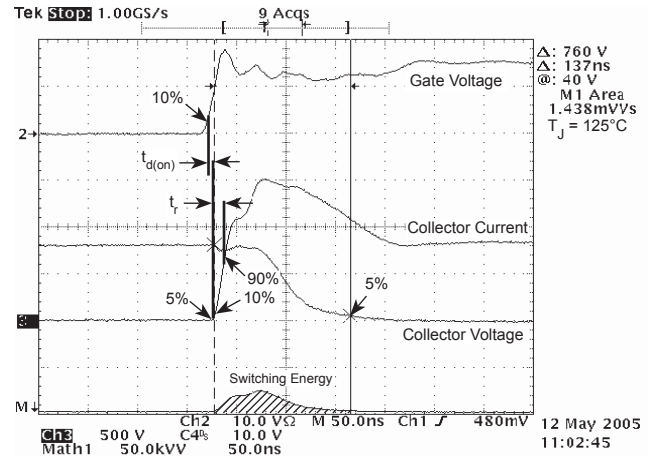


Figure 22, Turn-on Switching Waveforms and Definitions

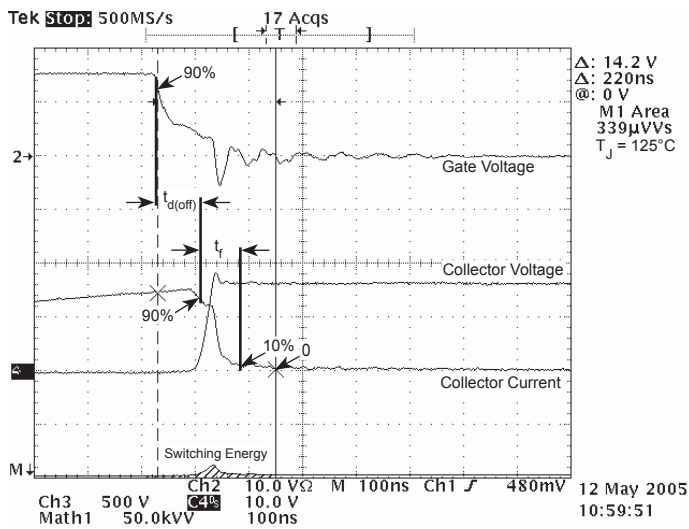


Figure 23, Turn-off Switching Waveforms and Definitions

ULTRAFAST SOFT RECOVERY ANTI-PARALLEL DIODE

MAXIMUM RATINGS All Ratings: T_C = 25°C unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT15GT120B_SRDQ1(G)			UNIT
I _F (AV)	Maximum Average Forward Current (T _C = 127°C, Duty Cycle = 0.5)		15		Amps
I _F (RMS)	RMS Forward Current (Square wave, 50% duty)		29		
I _{FSM}	Non-Repetitive Forward Surge Current (T _J = 45°C, 8.3ms)		110		

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions		MIN	TYP	MAX	UNIT
V _F	Forward Voltage	I _F = 15A		2.8		Volts
		I _F = 30A		3.4		
		I _F = 15A, T _J = 125°C		2.45		

DYNAMIC CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
t _{rr}	Reverse Recovery Time	I _F = 1A, di _F /dt = -100A/μs, V _R = 30V, T _J = 25°C	-	21		ns
t _{rr}	Reverse Recovery Time	I _F = 15A, di _F /dt = -200A/μs V _R = 800V, T _C = 25°C	-	240		
Q _{rr}	Reverse Recovery Charge		-	260		nC
I _{RRM}	Maximum Reverse Recovery Current	I _F = 15A, di _F /dt = -200A/μs V _R = 800V, T _C = 125°C	-	3	-	Amps
t _{rr}	Reverse Recovery Time		-	290		ns
Q _{rr}	Reverse Recovery Charge		-	960		nC
I _{RRM}	Maximum Reverse Recovery Current	I _F = 15A, di _F /dt = -1000A/μs V _R = 800V, T _C = 125°C	-	6	-	Amps
t _{rr}	Reverse Recovery Time		-	130		ns
Q _{rr}	Reverse Recovery Charge		-	1340		nC
I _{RRM}	Maximum Reverse Recovery Current		-	19		Amps

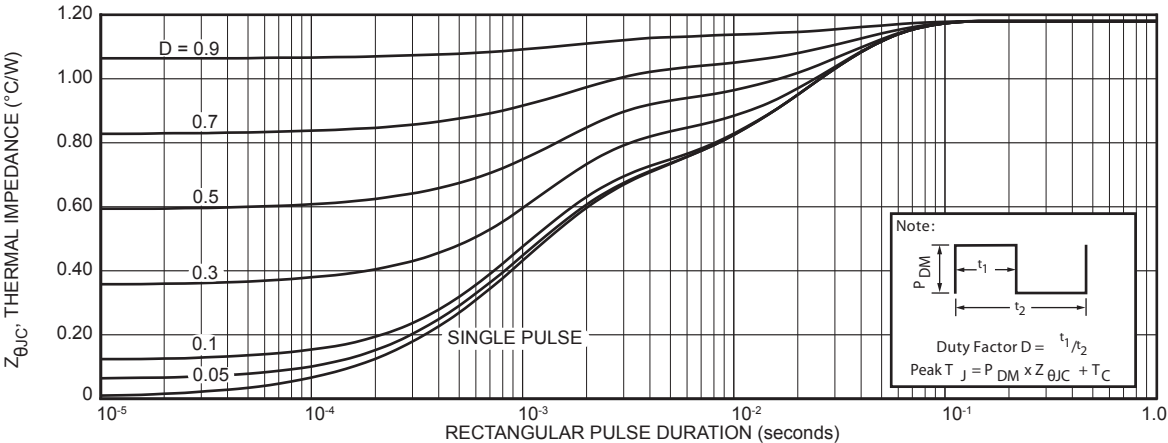


FIGURE 24. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

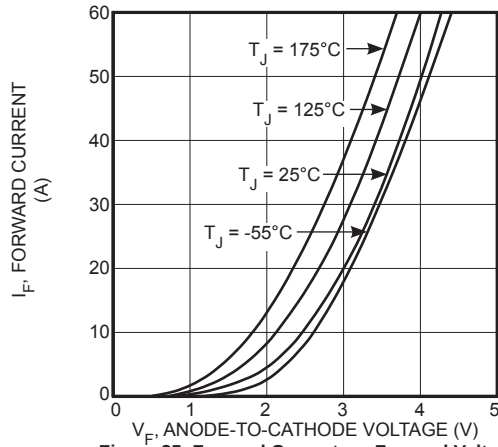


Figure 25. Forward Current vs. Forward Voltage

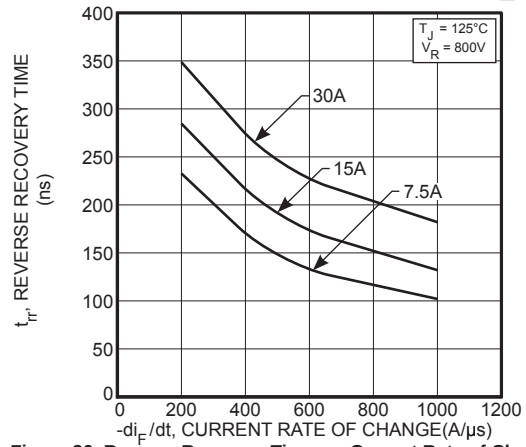


Figure 26. Reverse Recovery Time vs. Current Rate of Change

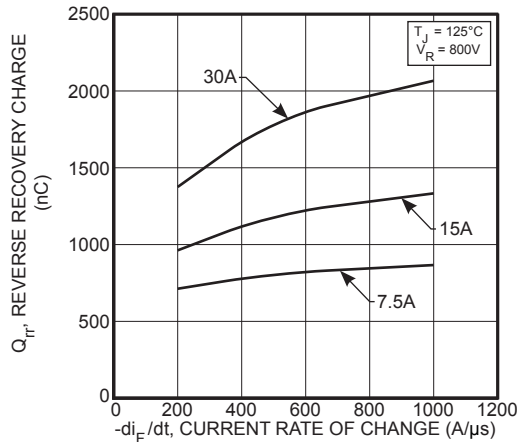


Figure 27. Reverse Recovery Charge vs. Current Rate of Change

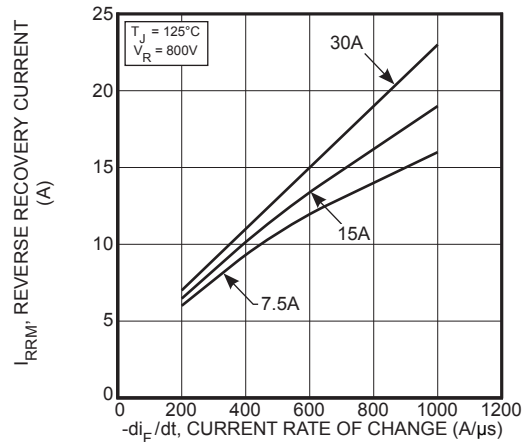


Figure 28. Reverse Recovery Current vs. Current Rate of Change

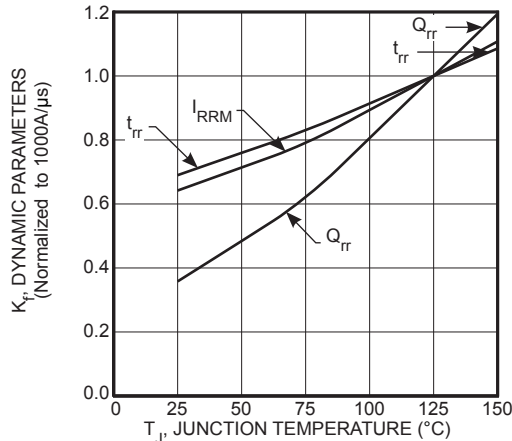


Figure 29. Dynamic Parameters vs. Junction Temperature

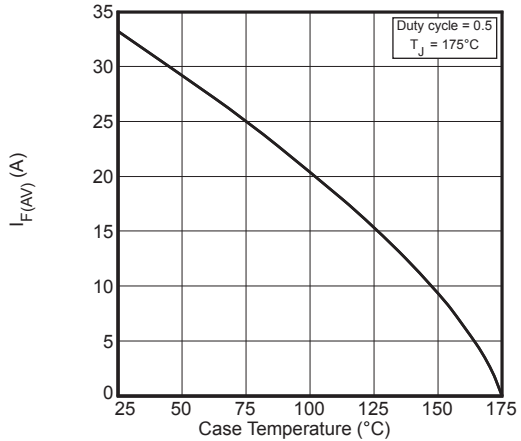


Figure 30. Maximum Average Forward Current vs. Case Temperature

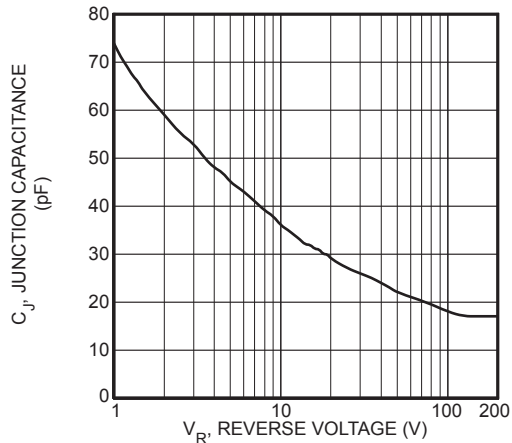


Figure 31. Junction Capacitance vs. Reverse Voltage

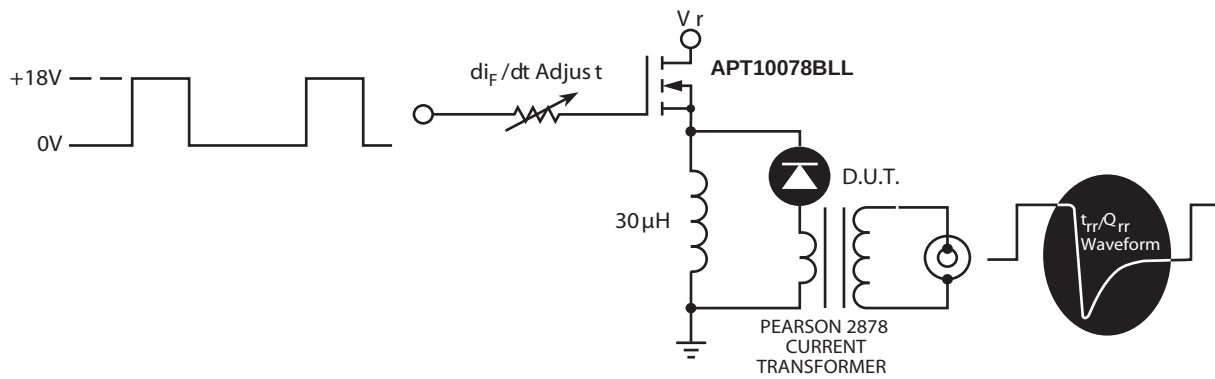


Figure 32. Diode Test Circuit

- 1 I_F - Forward Conduction Current
- 2 di_F/dt - Rate of Diode Current Change Through Zero Crossing.
- 3 I_{RRM} - Maximum Reverse Recovery Current
- 4 t_{rr} - Reverse Recovery Time measured from zero crossing where diode current goes from positive to negative, to the point at which the straight line through I_{RRM} and $0.25 I_{RRM}$ passes through zero.
- 5 Q_{rr} - Area Under the Curve Defined by I_{RRM} and t_{rr} .

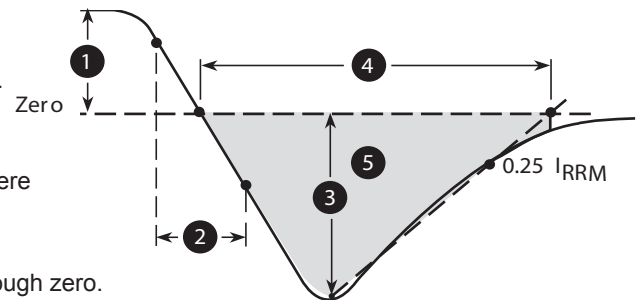
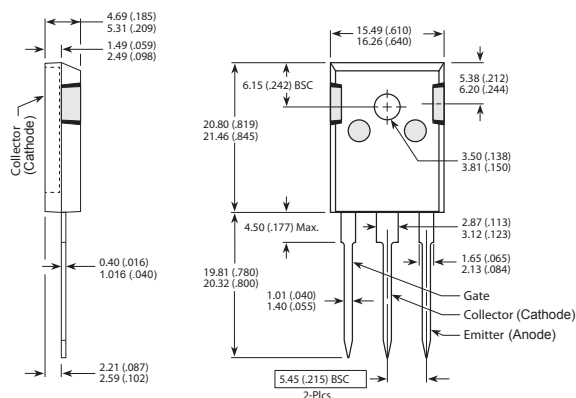


Figure 33. Diode Reverse Recovery Waveform Definition

TO-247 Package Outline

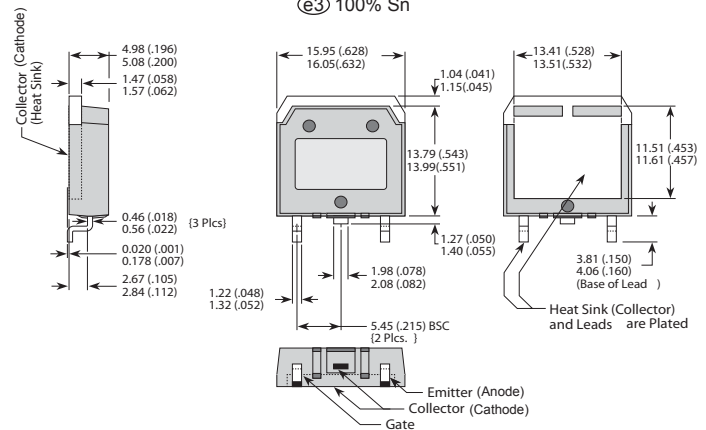
① SAC: Tin, Silver, Copper



Dimensions in Millimeters (Inches)

D³PAK Package Outline

③ 100% Sn



Dimensions in Millimeters (Inches)

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